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IN THE CLAIMS

Please amend the claims as follows:

subg1
1. (AMENDED) An apparatus comprising:
a circuit configured to generate a plurality of
identification (ID) codes in response to one or more voltage levels
on one or more inputs; and

5 a package comprising one or more pins dedicated to
providing said one or more voltage levels to respective ones of
said one or more inputs, wherein said one or more voltage levels
determine which of said plurality of identification codes is
generated by said circuit.

2. (AMENDED) The apparatus according to claim 1,
wherein said ID codes comprise a silicon ID of an electronic part.

3. (AMENDED) The apparatus according to claim 1,
wherein said circuit is further configured to generate said
plurality of ID codes in response to one or more options selected
from the group consisting of metal options, bond options, and hard
5 coded options.

4. (AMENDED) The apparatus according to claim 1,
wherein said one or more pins are connected to either a voltage

supply power or a voltage supply ground according to markings on said package.

5. (AMENDED) The apparatus according to claim 1, wherein each of said plurality of ID codes comprises a part number for said apparatus.

6. (AMENDED) The apparatus according to claim 5, wherein said part number is combined with other identification codes.

7. (AMENDED) The apparatus according to claim 6, wherein said other ID codes comprise one or more codes selected from the group consisting of a version number and a manufacturing number.

8. (AMENDED) The apparatus according to claim 1, wherein said ID code is captured in a register in response to an identification request.

9. The apparatus according to claim 8, wherein said register comprises a JTAG ID code register.

10. The apparatus according to claim 1, wherein said apparatus comprises a programmable logic device (PLD).

11. (AMENDED) The apparatus according to claim 3, wherein said metal options are set to indicate an operating voltage of said apparatus.

12. (AMENDED) The apparatus according to claim 3, wherein said bond options are set based on a style of said package of said apparatus.

13. The apparatus according to claim 1, wherein said pins are labeled as either a first or a second supply voltage.

14. The apparatus according to claim 13, wherein said pins are labeled as either said first or said second supply voltage based on characteristics of said apparatus.

15. (AMENDED) The apparatus according to claim 14, wherein said characteristics comprise one or more characteristics selected from the group consisting of volatility, price, package, metal options, operating voltage, internal structure, part category and density.

16. (AMENDED). A method of providing a plurality of identification codes for a single die and package combination comprising the steps of:

(A) dedicating one or more pins of said package to
5 selecting any of a plurality of identification codes;

(B) generating said plurality of identification codes in response to voltage levels on said one or more pins; and

(C) providing an indication of said voltage levels to be applied to each of said one or more pins.

17. (AMENDED) The method according to claim 16, wherein the step (B) further comprises the steps of:

determining said voltage levels on said pins;

determining a state of one or more metal options;

5 determining a state of one or more bond options; and

generating said identification code in response to a logical combination of a result of each determining step.

18. (AMENDED) The method according to claim 16, further comprising the step of:

presenting a selected identification code in response to an identification request.

19. The method according to claim 18, wherein said identification request comprises a JTAG ID code instruction.

20. (AMENDED) An apparatus comprising:

means for generating a plurality of identification codes in response to one or more voltage levels asserted at one or more inputs; and

5 means for packaging said generating means comprising one or more pins dedicated to providing said one or more voltage levels to respective ones of said one or more inputs, wherein said one or more voltage levels determine which of said plurality of identification codes is generated by said circuit.

Q2 (continued)
[Please add the following new claims:]

21. (NEW) The apparatus according to claim 1, wherein said apparatus can present any of said plurality of identification codes after packaging.

22. (NEW) The apparatus according to claim 1, wherein said apparatus changes identification code in response to a change in said one or more voltage levels applied to said one or more pins.

23. (NEW) The apparatus according to claim 1, wherein said package further comprises one or more pins dedicated to a test access port, at least one voltage supply pin and at least one ground pin.

24. (NEW) The method according to claim 16, further comprising:

marking voltage level indications on said package after
5 assembly to select a particular one of said plurality of identification codes for said die and package combination.

25. (NEW) The method according to claim 16, further comprising:

changing voltage level indications provided to select different identification codes.

VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (AMENDED) An apparatus comprising:

a circuit configured to [select one of] generate a [number] plurality of identification (ID) codes in response [a] to one or more voltage [level at] levels on one or more inputs; and

5 a package comprising one or more pins dedicated to providing said one or more voltage levels to respective ones of said one or more inputs, wherein said one or more voltage levels determine which of said plurality of identification codes is generated by said circuit.

2. (AMENDED) The apparatus according to claim 1, wherein said ID [code is] codes comprise a silicon ID of an electronic part.

3. (AMENDED) The apparatus according to claim 1, wherein said [number] circuit is further configured to generate said plurality of ID codes [are programmed using] in response to one or more options selected from the group consisting of metal

5 options, bond options, and hard coded options.

4. (AMENDED) The apparatus according to claim 1, wherein said one or more pins are connected to either a voltage

supply power or a voltage supply ground according to [package] markings on said package.

5. (AMENDED) The apparatus according to claim 1, wherein each of said plurality of ID [code] codes comprises a part number for said apparatus.

6. (AMENDED) The apparatus according to claim 5, wherein said [ID code] part number is combined with other identification codes.

7. (AMENDED) The apparatus according to claim 6, wherein said other ID codes comprise one or more codes selected from the group consisting of a version number and a [manufacture] manufacturing number.

8. (AMENDED) The apparatus according to claim 1, wherein said ID code is captured in a register in response to an identification request.

11. (AMENDED) The apparatus according to claim [1] 3, wherein said metal options are set to indicate an operating voltage of said apparatus.

12. (AMENDED). The apparatus according to claim [1] 3,
wherein said bond options are set based on a style of said package
of said apparatus.

15. (AMENDED) The apparatus according to claim 14,
wherein said characteristics comprise one or more characteristics
selected from the group consisting of volatility, price, package,
metal options, operating voltage, internal structure, part category
5 and density.

16. (AMENDED) A method of [selecting one of] providing
a [number] plurality of identification codes for a single die and
package combination comprising the steps of:

(A) [asserting a first or a second voltage level on]
5 dedicating one or more pins of said package to selecting any of a
plurality of identification codes; [and]

(B) generating said [one of a number of] plurality of
identification codes in response to [said] voltage levels on said
one or more pins; and

10 (C) providing an indication of said voltage levels to be
applied to each of said one or more pins.

17. (AMENDED) The method according to claim 16, wherein
the step (B) further comprises the [sub-steps] steps of:

[(B-1)] determining said voltage levels on said pins;
[(B-2)] determining a state of one or more metal
5 options;
[(B-3)] determining a state of one or more bond
options; and
[(B-4)] generating [an] said identification code in
response to a logical combination of a result of each determining
10 step [the determinations of sub-steps (B-1) through [(B-2)]].

18. (AMENDED) The method according to claim 16, further
comprising the step of:

[(C)] presenting [said] a selected identification
code in response to an identification request.

20. (AMENDED) An apparatus comprising:

means for generating a [number] plurality of
identification codes in response to [a] one or more voltage [level]
levels asserted at one or more [pins] inputs; and

5 means for [determining a voltage level to assert at]
packaging said generating means comprising one or more pins
dedicated to providing said one or more voltage levels to
respective ones of said one or more inputs, wherein said one or
more voltage levels determine which of said plurality of
10 identification codes is generated by said circuit.

21. (NEW) The apparatus according to claim 1, wherein said apparatus can present any of said plurality of identification codes after packaging.

22. (NEW) The apparatus according to claim 1, wherein said apparatus changes identification code in response to a change in said one or more voltage levels applied to said one or more pins.

23. (NEW) The apparatus according to claim 1, wherein said package further comprises one or more pins dedicated to a test access port, at least one voltage supply pin and at least one ground pin.

24. (NEW) The method according to claim 16, further comprising:

5 marking voltage level indications on said package after assembly to select a particular one of said plurality of identification codes for said die and package combination.

25. (NEW) The method according to claim 16, further comprising:

changing voltage level indications provided to select different identification codes.